IPC ASSOCIATION ELECTRONICS	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved u international and Pan-American copyright conventions.			ider both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
1752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typhttp://www.ipc.org/IPC-175x Distribute								rials and M	ials and Mfg Information				
Supplier	Information														
Company name*			Company unique ID			1	Unique ID Authority				Respon	Response Date*			
onsemi										2024-05	2024-05-06				
Contact Na	ame	Title - Contact]	Phone - Contact*				Email -	Email - Contact*				
Product-E	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
Authorized	d Representative*	Title - Representative]	Phone - Representative*				Email -	Email - Representative*				
Product-E	Env-Stewards		Product Enviro Compliance				NA				Produc	Product-Env-Stewards@onsemi.com			
	Requester Item Number Mfr Item		Number Mfr Item Name				Effective Da	te Versi	on I	Manufacturing Site		Weight*	UOM	Unit Type	
		NVATS5A107PLZT4 PCH 4.5V DR		PCH 4.5V DRIVE	VE SERIES		2024-05-06		•	CNG		267.68	mg	Each	
Aanufa	cturing Process Information	ation													
	Terminal Plating / Grid Array Material Term			rminal Base Alloy J-STD-020 MSL Rat			ing Peak Process Body Temperature Max Time at Peal				k Tempera	ture Nur	nber of Reflow Cy	eles	
contains Bi			U Alloy 1			260 C		С	30	seco	nds 3				
omments															
evel 1 - ma	aximum time at peak tempera	ture during sol	dering is 10-3	0 seconds						·			·		
or more i	nformation regarding materia	l composition	please refer to	page 3			·								

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated diphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale app											
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	es per the definition above except for selected exemp	otions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature Ra	astislav Drska	-6_									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	5.07	mg	Supplier	Silicon (Si)	7440-21-3		5.07	mg
Die Attach	5.43		Supplier	Silver (Ag)	7440-22-4		0.1075	mg
			A	Lead (Pb)	7439-92-1	7a	5.051	mg
			Supplier	Tin (Sn)	7440-31-5		0.2715	mg
Lead Frame	151.25		Supplier	Tin (Sn)	7440-31-5		0.2269	mg
			Supplier	Copper (Cu)	7440-50-8		151.0231	mg
Mold Compound-Black	102.62			Phenolic Resin	proprietary data		2.5655	mg
			Supplier	Epoxy Phenol Resin	Proprietary Data		8.4662	mg
			Supplier	Carbon Black (C)	1333-86-4		0.5131	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		90.5621	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.5131	mg
Plating	3.31	mg	В	Bismuth (Bi)	7440-69-9		0.0199	mg
			Supplier	Tin (Sn)	7440-31-5		3.2901	mg